



Product Change Notification

Change Notification #: 115711 - 00

Change Title: Intel® Omni-Path Director Class Switch 100 Series 6 Slot Base 1MM 100SWD06B1N,
Intel® Omni-Path Director Class Switch 100 Series 24 Slot Base 1MM 100SWD24B1N,
Intel® Omni-Path Director Switch Management Module 100 Series 100SWDMGTSH,
Intel® Omni-Path Director Class Switch 100 Series 6 Slot FRU Chassis 100SWD06CHS,
Intel® Omni-Path Director Class Switch 100 Series 24 Slot FRU Chassis 100SWD24CHS
PCN 115711-00, Product Design, Label, Congatec* QA3E Card BIOS and Board Controller Firmware Update, Packaging Label Addition

Date of Publication: August 7, 2017

Key Characteristics of the Change:

Product Design, Label

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	September 04, 2017
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The date of "First Availability of Post-Conversion Material" is the projected date that a customer may expect to receive the Post-Conversion Materials. This date is determined by the projected depletion of inventory at the time of the PCN publication. The depletion of inventory may be impacted by fluctuating supply and demand, therefore, although customers should be prepared to receive the Post-Converted Materials on this date, Intel will continue to ship and customers may continue to receive the pre-converted materials until the inventory has been depleted.

Description of Change to the Customer:

The BIOS and Board Controller Firmware on the Congatec* QA3E card, located in the Omni-Path Director Switch Management Module, shall be updated to address erratum VLI89 of the Intel® Atom® Processor E3800 Series. A new label with text in Hebrew will be added to Director Switch exterior packaging.

Affected Product Code	Affected Intel MM	Product Description
100SWD06B1N	945676	Intel® Omni-Path Director Class Switch 100 Series 6 Slot Base 1MM 100SWD06B1N
100SWD24B1N	945677	Intel® Omni-Path Director Class Switch 100 Series 24 Slot Base 1MM 100SWD24B1N
100SWDMGTSH	945776	Intel® Omni-Path Director Switch Management Module 100 Series 100SWDMGTSH
100SWD06CHS	947192	Intel® Omni-Path Director Class Switch 100 Series 6 Slot FRU Chassis 100SWD06CHS
100SWD24CHS	947193	Intel® Omni-Path Director Class Switch 100 Series 24 Slot FRU Chassis 100SWD24CHS

Overview of Changes:

Change 1: For Omni-Path Director Class Switches and the Management Module, the BIOS and Board Controller Firmware on the Congatec* QA3E card shall be updated to address erratum VLI89 of the Intel® Atom® Processor E3800 Series.

Change 2: For Omni-Path Director Class Switches and Chassis, the exterior packaging will be updated with an additional label in Hebrew.

Product Change Details:

Change 1: The Congatec* QA3E card's BIOS and Board Controller Firmware shall be updated to address VLI89 of Intel® Atom® Processor E3800 Series.

The Congatec* QA3E card is part of the Q7 Management Card which is in the Director Switch Management Module. The Director Switch Management Module is sold as a standalone product (100SWDMGTSH) and is included with Director Class Switches (100SWD06B1N and 100SWD24B1N.) Refer to the Q7 Management Card Change Summary below for additional details.

Q7 Management Card Change Summary

	Pre-Change	Post-Change
Intel Part Number	H94189-001	H94189-002
Description	Conga-QA3E/E3815-2G eMMC4 INT1	Conga-QA3E/E3815-2G eMMC4 INT1
Vendor	Congatec AG*	Congatec AG
Congatec Part Number	618104	618104
Congatec Revision	A.0	A.1
BIOS	QA3ER915.BIN	QA3ER962.BIN
Board Controller Firmware	CGBCP420	CGBCP429

Change 2: For Omni-Path Director Class Switches (100SWD06B1N, 100SWD24B1N) and Chassis (100SWD06CHS, 100SWD24CHS), a packaging label with text in Hebrew will be added to support shipments into Israel, per SII, the Standards Institute of Israel.

For 100SWD06B1N and 100SWD06CHS, the following label will be added to the exterior packaging:



For 100SWD24B1N and 100SWD24CHS, the following label will be added to the exterior packaging:



Customer Impact of Change and Recommended Action:

Intel is not recommending additional qualification of these changes by customers.

There is no change to the switch Intel Material Master (MM) numbers.

Please contact your local Intel Field Sales Representative if you have any questions about this change.

Milestone dates are estimates and subject to change based on business and operational conditions.

* Other names and brands may be claimed as the property of others.

Products Affected:

Affected Product Code	Affected Intel MM	Product Description
100SWD06B1N	945676	Intel® Omni-Path Director Class Switch 100 Series 6 Slot Base 1MM 100SWD06B1N
100SWD24B1N	945677	Intel® Omni-Path Director Class Switch 100 Series 24 Slot Base 1MM 100SWD24B1N
100SWDMGTSH	945776	Intel® Omni-Path Director Switch Management Module 100 Series 100SWDMGTSH
100SWD06CHS	947192	Intel® Omni-Path Director Class Switch 100 Series 6 Slot FRU Chassis 100SWD06CHS
100SWD24CHS	947193	Intel® Omni-Path Director Class Switch 100 Series 24 Slot FRU Chassis 100SWD24CHS

Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre Change MM# Rev	Post Change MM# Rev	Pre Change TA	Pre Change AS	Post Change TA	Post Change AS
100SWD06B1N	945676	13	14	J12783-012	J11517-012	J12783-013	J11517-013
100SWD24B1N	945677	13	14	J12778-012	H89346-014	J12778-013	H89346-015
100SWDMGTSH	945776	06	07	H87892-008	H60416-010	H87892-009	H60416-011
100SWD06CHS	947192	06	07	J18616-005	J19700-004	J18616-006	No Change
100SWD24CHS	947193	06	07	J18618-005	J18617-004	J18618-006	No Change

PCN Revision History:

Date of Revision:

August 7, 2017

Revision Number:

00

Reason:

Originally Published PCN



Product Change Notification

115711 - 00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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